



Patent Application No. 10/618,536
Customer Number: 42717

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Jing Cheng Lin, et al.	§	Docket No.:	24061.485
		§		(TSMC2002-0360)
Serial No.:	10/618,536	§		
		§	Examiner:	Thien F. Tran
Filing Date:	June 11, 2003	§		
		§	Art Unit:	2811
For:	Adhesion Copper and Etch Stop	§		
	Layer for Copper Alloy	§	Conf. No.:	5026
		§		

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop: Amendment
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed August 20, 2004, applicant hereby elects, Group II, Claims 1-18 and 30-32, which is drawn to a process for making semiconductor devices.

Applicant's election is made with traverse on the grounds that the embodiments delineated by the examiner are not patentably distinct and therefore constitute a single invention concept.

An early action on the merits is respectfully requested.

Respectfully submitted,

David M. O'Dell
Reg. No. 42,044

Date: 10-20-04

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop: Amendment, Commissioner For Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date below.

Bonnie Boyce
Name

10-20-04
Date